

PCN 15_0163 ADG836L Wafer Fabrication Change from TSMC Fab 7A to TSMC Fab 11

QUALIFICATION RESULTS			
TEST	SPECIFICATION	SAMPLE SIZE	RESULTS
High Temperature Operating Life (HTOL)*	JEDEC <i>JESD22-A108</i>	2x45 7x77	Pass
Highly Accelerated Stress Test (HAST)*	JEDEC <i>JESD22-A110</i>	4x77 5x45	Pass
ELF	MIL-STD-883, <i>Method 1015</i>	3x667 3x667 3x667	Pass
High Temperature Storage Life (HTSL)	JEDEC <i>JESD22-A103</i>	1x77 3x45	Pass
Latch-Up	JEDEC <i>JESD78</i>	3	Pass
Electrostatic Discharge <i>Human Body Model</i>	ESDA/JEDEC <i>JS-001</i>	3/voltage	Pass_4000V
Electrostatic Discharge <i>Machine Model</i>	JEDEC <i>JESD22-A115</i>	3/voltage	Pass_200V
Electrostatic Discharge <i>Field-Induced Charged Device Model</i>	JEDEC <i>JESD22-C101</i>	3/voltage	Pass_1250V

*Preconditioned per JEDEC/IPC J-STD-020